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YU et al.(10) **Pub. No.: US 2022/0416722 A1**(43) **Pub. Date: Dec. 29, 2022**(54) **AMPLIFIER CIRCUIT WITH AN ENVELOPE
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(57)

ABSTRACT

Amplifier circuits, radio communication circuits, radio communication devices, and methods provided in this disclosure provide an amplifier circuit. The amplifier circuit may include an amplifier configured to amplify an input signal to provide an output signal. The amplifier circuit may further include an amplifier stack including a first transistor coupled to the amplifier. The amplifier stack may be configured to receive the output signal to amplify the output signal. The amplifier stack may be configured to receive an input control signal to control the first transistor based on an envelope of the input signal.

